

PATENT ASSIGNMENT COVER SHEET

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NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KEISHI KITAMURA	01/26/2016
YOSHIHIRO MIZUTANI	01/28/2016
YASUTO TAKEDA	01/25/2016
HIROKI HIRAI	01/25/2016
TETSUJI TANAKA	01/28/2016
HIROYOSHI MAESOB	01/28/2016
KOSUKE SONE	01/28/2016
RECEIVING PARTY DATA	
Name:	AUTONETWORKS TECHNOLOGIES, LTD.
Street Address:	1-14, NISHISUEHIRO-CHO
City:	YOKKAICHI, MIE
State/Country:	JAPAN
Postal Code:	510-8503
Name:	SUMITOMO WIRING SYSTEMS, LTD.
Street Address:	1-14, NISHISUEHIRO-CHO
City:	YOKKAICHI, MIE
State/Country:	JAPAN
Postal Code:	510-8503
Name:	SUMITOMO ELECTRIC INDUSTRIES, LTD.
Street Address:	5-33, KITAHAMA 4-CHOME, CHUO-KU
City:	OSAKA-SHI, OSAKA
State/Country:	JAPAN
Postal Code:	541-0041
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15027020
CORRESPONDENCE DATA	
Fax Number:	(212)725-2452

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2127252450
Email: email@hpiplaw.com
Correspondent Name: HESPOS & PORCO LLP
Address Line 1: 110 WEST 40TH STREET
Address Line 2: SUITE 2501
Address Line 4: NEW YORK, NEW YORK 10018

ATTORNEY DOCKET NUMBER:	FPCT15-470US
NAME OF SUBMITTER:	GERALD E. HESPOS
SIGNATURE:	/Gerald E. Hespos/
DATE SIGNED:	04/04/2016

Total Attachments: 2

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ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignees, 1) AUTONETWORKS TECHNOLOGIES, LTD., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi, Mie, 510-8503 Japan, 2) Sumitomo Wiring Systems, Ltd., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi, Mie, 510-8503 Japan and 3) SUMITOMO ELECTRIC INDUSTRIES, LTD., a corporation organized under the laws of Japan, located at 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka, 541-0041 Japan, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignee the entire right, title and interest in and to the invention or improvement entitled, "CONNECTOR STRUCTURE AND WIRING HARNESS", said invention being fully described and/or claimed in the application for Letters Patent of the United States of America, executed this date, in and for the United States and all foreign countries, the same to be held and enjoyed by said assignee, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

And Said Assignee Is Hereby Authorized to make application for and to receive Letters Patent for said invention in any of said countries at its election.

And By This Covenant The Undersigned will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patent which may be granted therefor to said Assignee, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patent to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignee, its successors, assigns or other legal representatives.

And The Commissioner Of Patents Is Hereby Authorized And Requested to issue any and all Letters Patent of the United States for said invention, to said assignee.

January 26, 2016
Date

January 28, 2016
Date

January 25, 2016
Date

January 25, 2016
Date

January 28, 2016
Date

Keishi Kitamura
Keishi Kitamura

Yoshihiro Mizutani
Yoshihiro Mizutani

Yasuto Takeda
Yasuto Takeda

Hiroki Hirai
Hiroki Hirai

Tetsuji Tanaka
Tetsuji Tanaka

January 28, 2016
Date

January 28, 2016
Date

Hiro Yoshi Maesoba
Hiro Yoshi Maesoba

Kosuke Sone
Kosuke Sone